



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20250903001.1

**Qualification of CDAT as an additional Assembly site for the Select Devices
Change Notification / Sample Request**

Date: September 04, 2025

To: Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **60** days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **60 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20250903001.1**Attachment: 1****Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS564255DRLR	NULL
TPS563257DRLR	NULL
TPS564252DRLR	NULL
TPS564257DRLR	NULL
TPS563252DRLR	NULL
TPS562242DRLR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN# 20250903001.1			PCN Date:	September 04, 2025
Title:	Qualification of CDAT as an additional Assembly site for select devices				
Customer Contact:	Change Management Team		Dept:	Quality Services	
Proposed 1st Ship Date:	March 03, 2026		Sample requests accepted until:	November 03, 2025*	
*Sample requests received after November 03, 2025 will not be supported.					
Change Type:	<input checked="" type="checkbox"/> Assembly Site <input type="checkbox"/> Design <input type="checkbox"/> Wafer Bump Material <input type="checkbox"/> Assembly Process <input type="checkbox"/> Data Sheet <input type="checkbox"/> Wafer Bump Process <input type="checkbox"/> Assembly Materials <input type="checkbox"/> Part number change <input type="checkbox"/> Wafer Fab Site <input type="checkbox"/> Mechanical Specification <input type="checkbox"/> Test Site <input type="checkbox"/> Wafer Fab Material <input checked="" type="checkbox"/> Packing/Shipping/Labeling <input type="checkbox"/> Test Process <input type="checkbox"/> Wafer Fab Process				
PCN Details					
Description of Change:					
Texas Instruments Incorporated is announcing the qualification of CDAT as an additional Assembly site for the devices listed below. No material differences between sites.					
Qual details are provided in the Qual Data Section.					
Reason for Change:					
Supply continuity					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Impact on Environmental Ratings					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.					
RoHS	REACH	Green Status	IEC 62474		
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change		
Changes to product identification resulting from this PCN:					
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)		Assembly City	
TIPI	PHI	PHL		Baguio City	
CDAT	CDA	CHN		Chengdu	
Sample product shipping label (not actual product label)					
 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: LBL: 5A (L)T0:1750 39	 	(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY(1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO:MLA (23L) ACO:MYS			
Product Affected:					
TPS562242DRLR	TPS563257DRLR	TPS564255DRLR			

TPS563252DRLR	TPS564252DRLR	TPS564257DRLR	
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Qualification Report

Approve Date 07-July-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS562242DRLR	Qual Device: TPS563252DRLR	Qual Device: TPS564252DRLR	Qual Device: TPS563252DRLR	QBS Reference: TPS613780WRTER01	QBS Reference: TPS562231DRLR	QBS Reference: TPS563249DDCR	QBS Reference: TPS564201DDCR	QBS Reference: TPS563302JER	QBS Reference: TPS56202DRLR	QBS Reference: TPS562A02DRLR
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-	-	-	-	-	-	3/23U0	-	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/23U0	3/23U0	-	-	-	-	-
UHAST	A3	Autoclave	121C/15psi ^g	96 Hours	-	-	-	-	-	-	-	-	-	3/23U0	-
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	-	-	-	-	-	3/23U0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	-	-	-	3/23U0	3/23U0	3/23U0	-	-	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	1/77/0	1/77/0	-	-	-	-	-	-	3/23U0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/23U0	3/23U0	3/23U0	-	3/23U0	1/77/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/77/0	-	-	-	-	-	-	-	-	-	1/77/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	3/23U0	3/23U0	3/23U0	3/23U0	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	3/1350	-	-	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	3/23U0	3/23U0	-	1/77/0	-	-
HTOL	B1	Life Test	150C	408 Hours	-	-	-	-	3/23U0	-	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0	-	-	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/150	-	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/150	3/66/0	3/66/0	3/66/0	-	1/22/0	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	-	3/30/0	3/15/0	-	-	1/5/0	-	-
ESD	E2	ESD CDM	1000 Volts	-	-	-	-	-	1/3/0	-	-	-	-	-	-
ESD	E2	ESD HBM	3000 Volts	-	-	-	-	-	1/3/0	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/6/0	-	-	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-	3/90/0	-	-	-	3/90/0	-	-
FTY	E6	Final Test Yield	-	-	-	-	1/1/0	1/1/0	-	-	-	-	3/3/0	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device TPS562242DRLR is qualified at MSL1 260C

Qual Device TPS563252DRLR is qualified at MSL1 260C

Qual Device TPS563257DRLR is qualified at MSL1 260C

Qual Device TPS564252DRLR is qualified at MSL1 260C

Qual Device TPS564255DRLR is qualified at MSL1 260C

Qual Device TPS564257DRLR is qualified at MSL1 260C

Qual Device TPS562242DRLR is qualified at MSL1 260C

Qual Device TPS563252DRLR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2411-001

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic

(family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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